S/N 10/750,224   **PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Alan M. Myers et al.	Examiner:	Tuan Quach
Serial No.:	10/750,224	Group Art Unit:	2826
Filed:	December 31, 2003	Docket:	884.855US1
Title:	APPARATUS AND METHOD INTEGRATING AN ELECTRO-OSMOTIC PUMP AND MICROCHANNEL ASSEMBLY INTO A DIE PACKAGE		
Assignee:	Intel Corporation	Customer Number: 21186	

INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), please charge Deposit Account No. 19-0743 in the amount of $180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

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Dkt: 884.855US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

ALAN M. MYERS ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
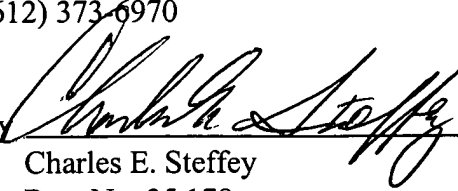Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, MN 55402
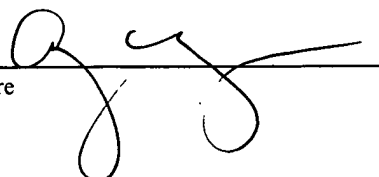(612) 373-6970

Date _January 27, 2006_   By_____
                            Charles E. Steffey
                            Reg. No. 25,179

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this __27th__ day of January, 2006.
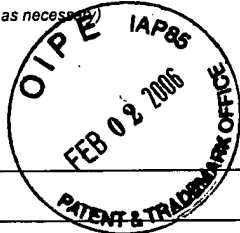
_____Amy Moriarty_____   _____
Name   Signature

Substitute for form 1449A/PTO **INFORMATION DISCLOSURE STATEMENT BY APPLICANT** *(Use as many sheets as necessary)*	Complete if Known	
	Application Number	10/750,224
	Filing Date	December 31, 2003
	First Named Inventor	Myers, Alan
	Group Art Unit	2826
	Examiner Name	Quach, Tuan
Sheet 1 of 1	**Attorney Docket No: 884.855US1**	

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-5,504,924	04/02/1996	Ohashi, Shingeo , et al.	09/26/1994
	US-5,763,951	06/09/1998	Hamilton, R. E., et al.	07/22/1996
	US-6,234,240	05/22/2001	Cheon, Kioan	07/01/1999
	US-6,277,629	08/21/2001	Wolf, Bernhard , et al.	06/01/2000
	US-6,285,550	09/04/2001	Belady, C. L.	03/10/2000
	US-6,507,492	01/14/2003	Morris, Terrel , et al.	02/15/2002
	US-6,606,251	08/12/2003	Kenny, Thomas , et al.	02/07/2002
	US-6,861,274	03/01/2005	List, R. S., et al.	03/28/2003

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No [1]	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T[2]
		BANERJEE, K , et al., "3-D ICs: a novel chip design for improving deep-submicrometer interconnect performance and systems-on-chip integration", Proceedings of the IEEE, 89(5), (May 2001),602-33	
		BURGREEN, D , et al., "Electrokinetic Flow in Ultrafine Capillary Slits", Journal of Physical Chemistry, 68(5), (1964),1084-1091	
		CHEN, CHUAN-HUA , et al., "A planar electroosmotic micropump", Journal of Microelectromechanical Systems, 11(6), (December 2002),672-83	
		LASER, D J., et al., "High-Frequency Actuation with Silicon Electroosmotic Micropumps", 2002 Solid-state sensor, actuator, and microsystems-Workshop, Hilton Head SC, (2002),231-234	
		MURAKAMI, YOICHI , et al., "Parametric Optimization of Multichanneled Heat Sinks for VLSI Chip Cooling", IEEE Transactions on Components and Packaging Technologies, 24, (2001),2-9	
		YAO, SHUHUAI , et al., "Porous glass electroosmotic pumps: Design and experiments", Journal of Colloid and Interface Science, 268(1), (143-153),December 1, 2003	
		YAO, SHUHUAI , et al., "Porous glass electroosmotic pumps: Theory", Journal of Colloid and Interface Science, 268(1), (December 1, 2003),133-142	
		ZHANG, LIAN , "Measurements and modeling of two-phase flow in microchannels with nearly constant heat flux boundary conditions", Journal of Microelectromechanical Systems, 11(1), (February 2002),12-19	

EXAMINER	DATE CONSIDERED